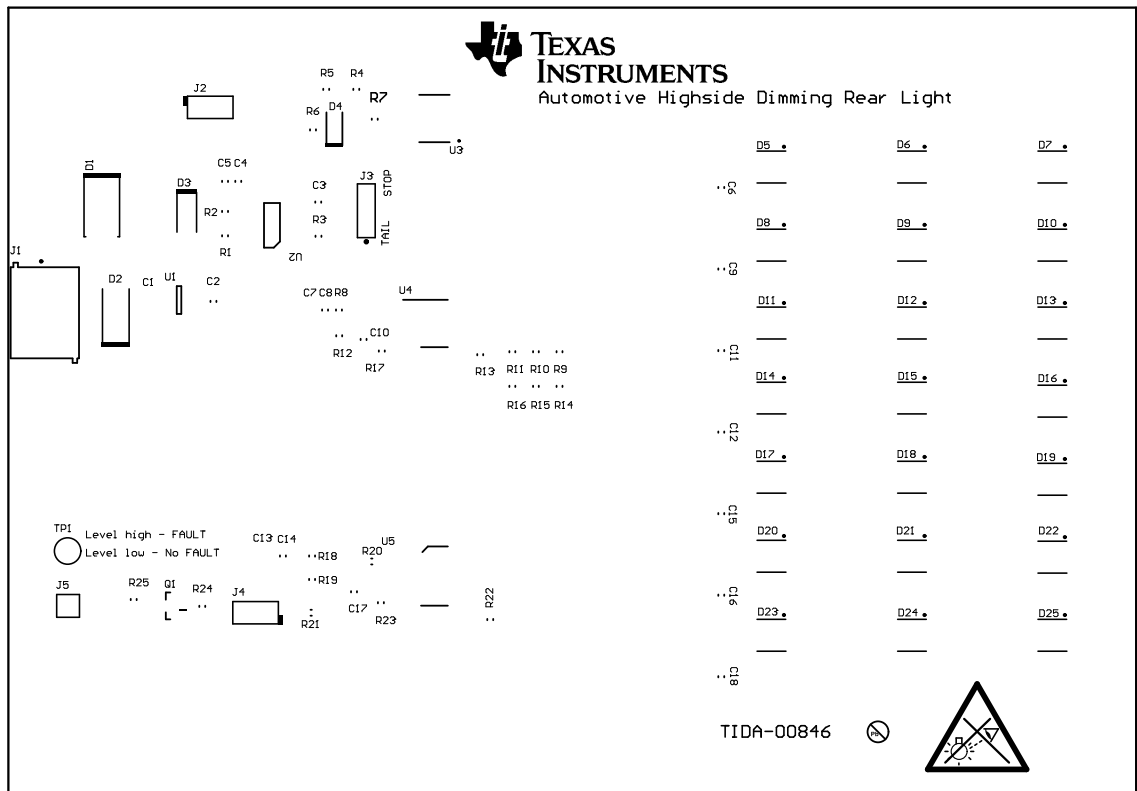




TEXAS INSTRUMENTS

Automotive Highside Dimming Rear Light



| | | |
|-----|-----|-----|
| D5 | D6 | D7 |
| D8 | D9 | D10 |
| D11 | D12 | D13 |
| D14 | D15 | D16 |
| D17 | D18 | D19 |
| D20 | D21 | D22 |
| D23 | D24 | D25 |



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: 001

REV: E1

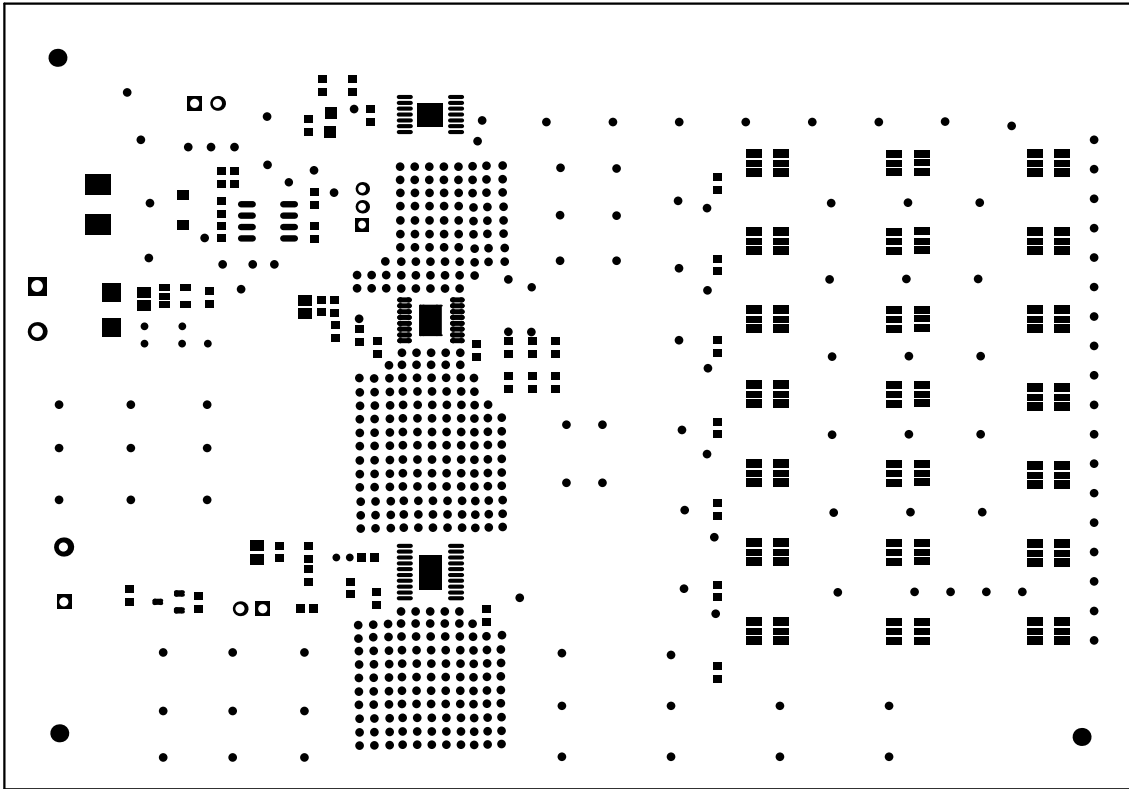
SUN REV: Not In VersionControl

LAYER NAME = Top Overlay

PLOT NAME = Top Overlay

GENERATED : 10/29/2015 12:14:19 PM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: 001

REV: E1

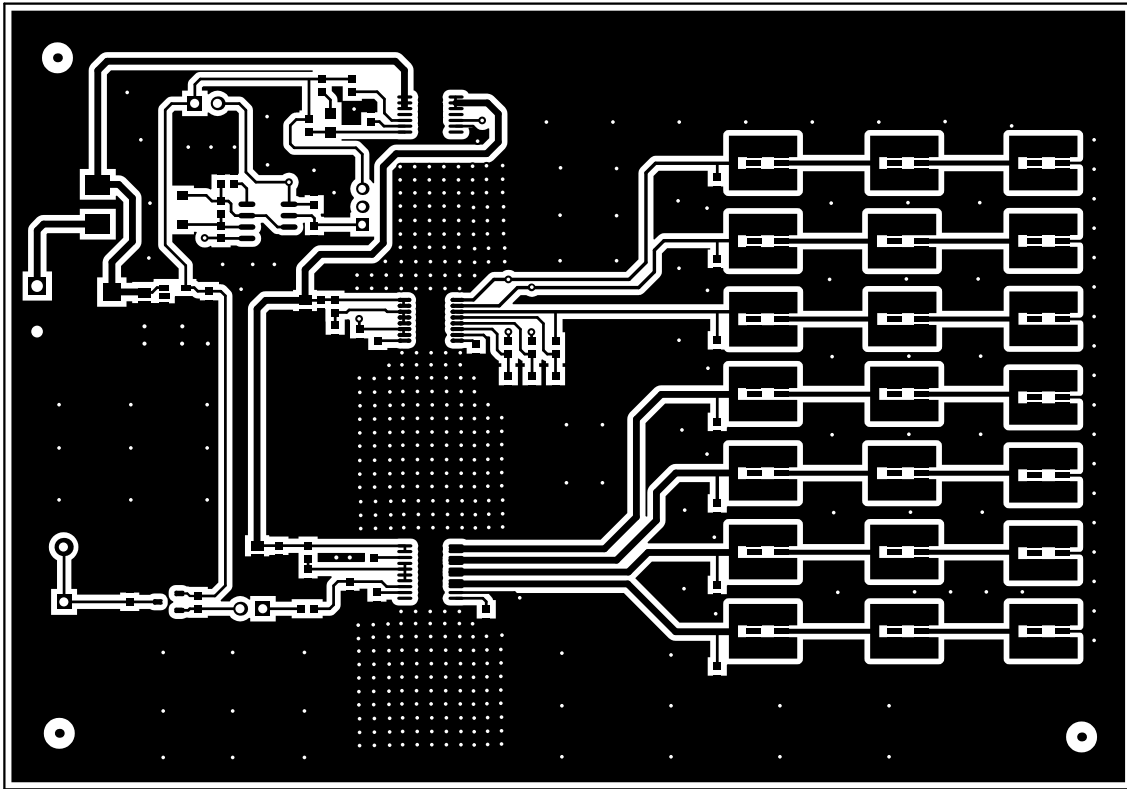
SUN REV: Not In VersionControl

LAYER NAME = Top Solder

PLOT NAME = Top Solder Mask

GENERATED : 10/29/2015 12:14:20 PM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: 001

REV: E1

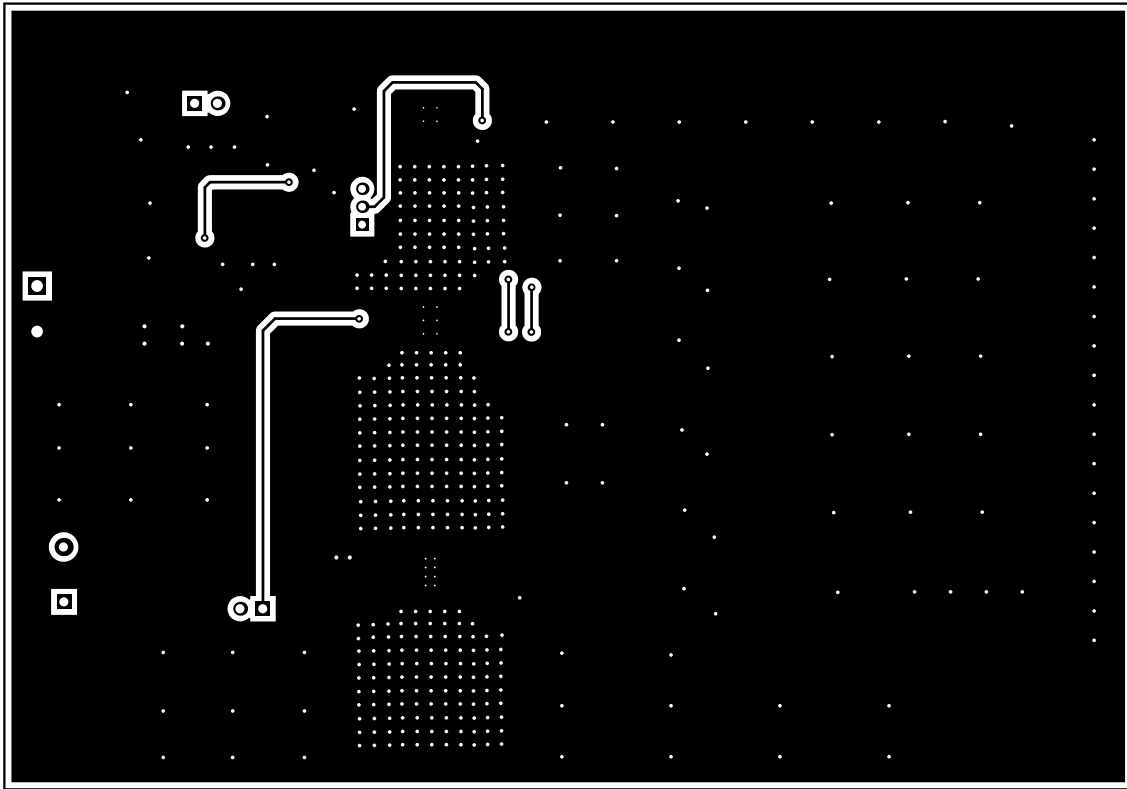
SUN REV: Not In VersionControl

LAYER NAME = Top Layer

PLOT NAME = Top Layer

GENERATED : 10/29/2015 12:14:20 PM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: 001

REV: E1

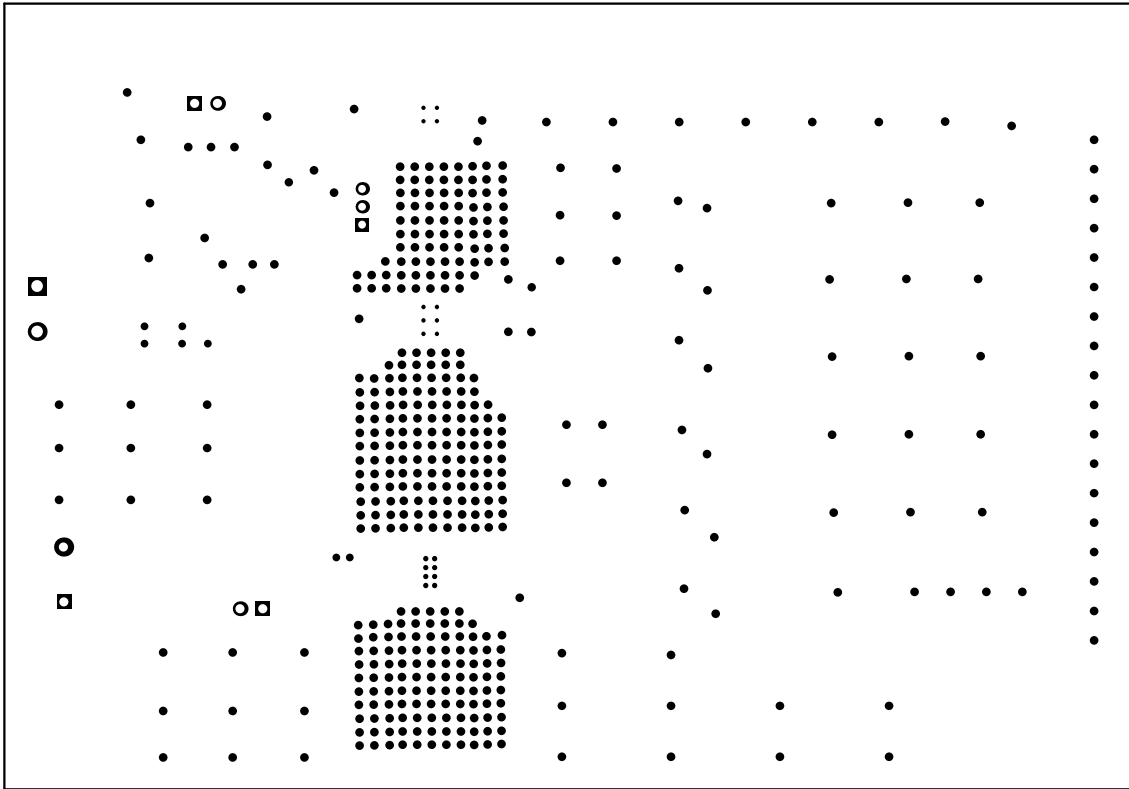
SUN REV: Not In VersionControl

LAYER NAME = Bottom Layer

PLOT NAME = Bottom Layer

GENERATED : 10/29/2015 12:14:21 PM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: 001

REV: E1

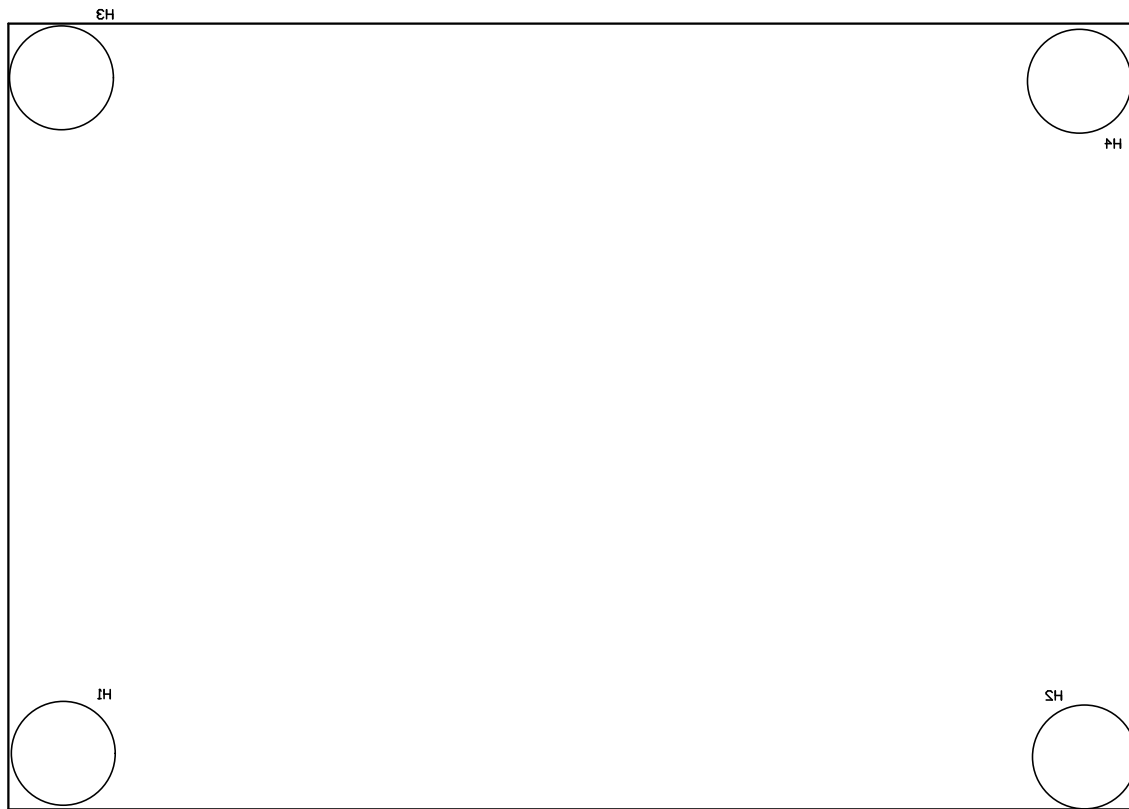
SUN REV: Not In VersionControl

LAYER NAME = Bottom Solder

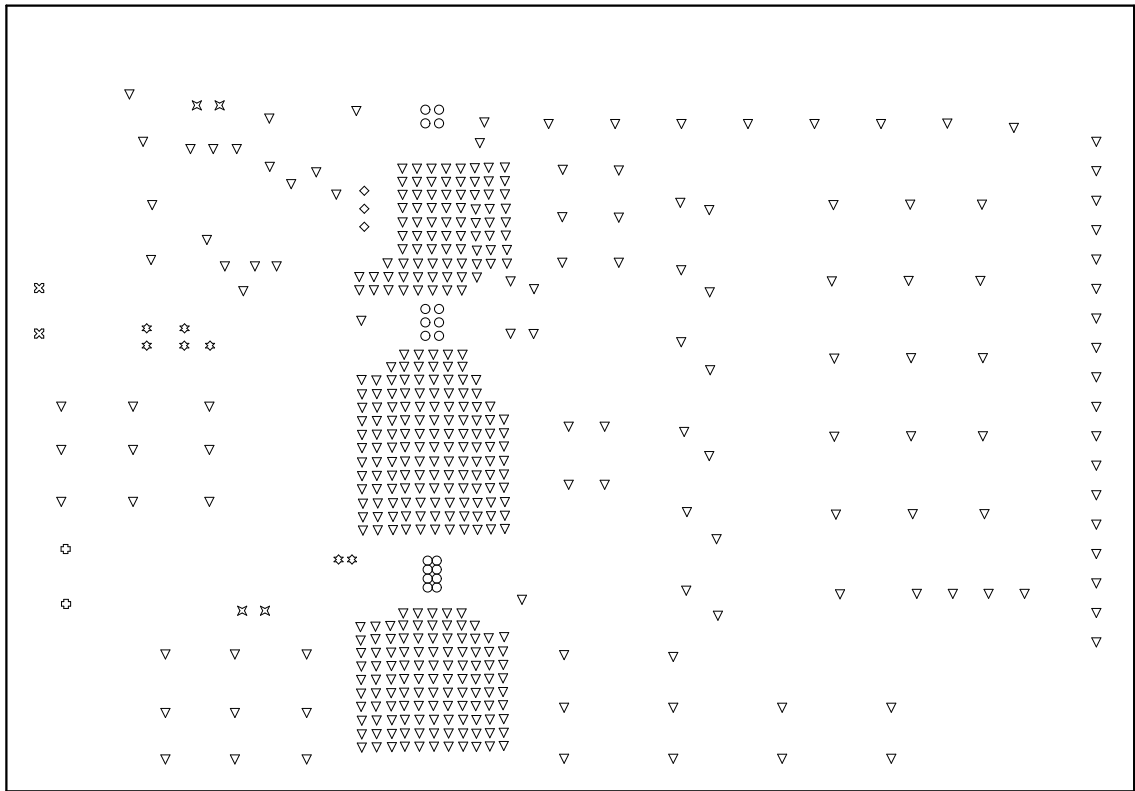
PLOT NAME = Bottom Solder Mask

GENERATED : 10/29/2015 12:14:22 PM

TEXAS INSTRUMENTS



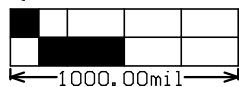
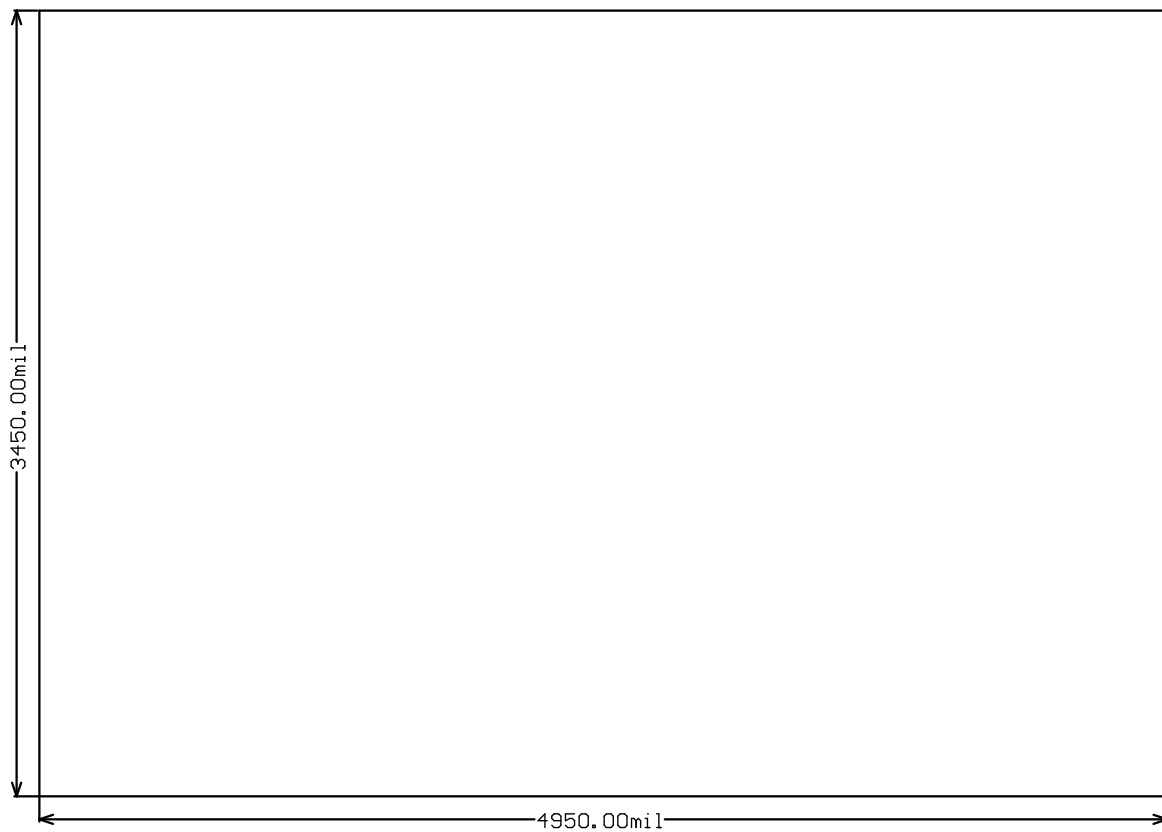
| | | | |
|----------------------------------|------------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: 001 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Overlay | | | |
| PLOT NAME = Bottom Overlay | GENERATED : 10/29/2015 12:14:22 PM | TEXAS INSTRUMENTS | |



| Symbol | Hit Count | Tool Size | Plated | Hole Type |
|-----------|-----------|--------------------|--------|-----------|
| ○ | 18 | 7.874mil (0.2mm) | PTH | Round |
| ▽ | 455 | 16mil (0.406mm) | PTH | Round |
| ☆ | 7 | 18mil (0.457mm) | PTH | Round |
| ◇ | 3 | 35mil (0.889mm) | PTH | Round |
| ⊠ | 2 | 40mil (1.016mm) | PTH | Round |
| ⊠ | 4 | 40.157mil (1.02mm) | PTH | Round |
| ⊠ | 2 | 51.181mil (1.3mm) | PTH | Round |
| 491 Total | | | | |

Drill Table

| | | | |
|----------------------------------|------------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: 001 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME = Drill Drawing | | | |
| PLOT NAME = Drill Drawing | GENERATED : 10/29/2015 12:14:23 PM | TEXAS INSTRUMENTS | |



| | | | |
|----------------------------------|------------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: 001 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME = M2 Board Dimensions | | | |
| PLOT NAME = Board Dimensions | GENERATED : 10/29/2015 12:14:23 PM | TEXAS INSTRUMENTS | |

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